

Yunkyum Kim

List of Publications by Year in descending order

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Version: 2024-02-01

11
papers

180
citations

1040056

9
h-index

1281871

11
g-index

11
all docs

11
docs citations

11
times ranked

121
citing authors

#	ARTICLE	IF	CITATIONS
1	Prediction of Phase Separation of Immiscible Ga-Tl Alloys. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2017, 48, 3130-3136.	2.2	4
2	Effect of Nickel Precoating on Wettability of Twinning-Induced Plasticity Steels by Liquid Zn-0.23Wt%PctAl. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2016, 47, 4960-4969.	2.2	4
3	Surface Tension of Liquid Fe-O Alloys: Revisiting Belton's Two-Step Adsorption Model. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2014, 45, 947-952.	2.1	14
4	Effect of dew point on the formation of surface oxides of twinning-induced plasticity steel. Materials Characterization, 2014, 89, 138-145.	4.4	20
5	The influence of the dew point on the wettability of twinning-induced-plasticity steels by liquid Zn~"0.23-wt% Al. Corrosion Science, 2014, 85, 364-371.	6.6	19
6	The influence of Mn Content on the wettability of dual-phase high-strength steels by liquid Zn~"0.23% Al. Journal of Materials Science, 2012, 47, 8477-8482.	3.7	9
7	Effect of Si content on wettability of dual phase high strength steels by liquid Zn-0.23 wt.%Al. Metals and Materials International, 2011, 17, 607-611.	3.4	17
8	Preparation and Thermal Analysis of Sn-Ag Nano Solders. Materials Transactions, 2010, 51, 2145-2149.	1.2	33
9	Wettability of MnxSiyOz by Liquid Zn-Al Alloys. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2010, 41, 872-875.	2.1	21
10	Improvement of the wettability of SiMn IF-HSS by liquid zinc by controlling the dew point of the annealing gas atmosphere. Journal of Materials Science, 2010, 45, 2112-2117.	3.7	19
11	Investigation of the Dynamic Reactive Wetting of Sn-Ag-Cu Solder Alloys on Ni(P)/Au Coated Cu Substrates. Materials Transactions, 2009, 50, 2695-2698.	1.2	20